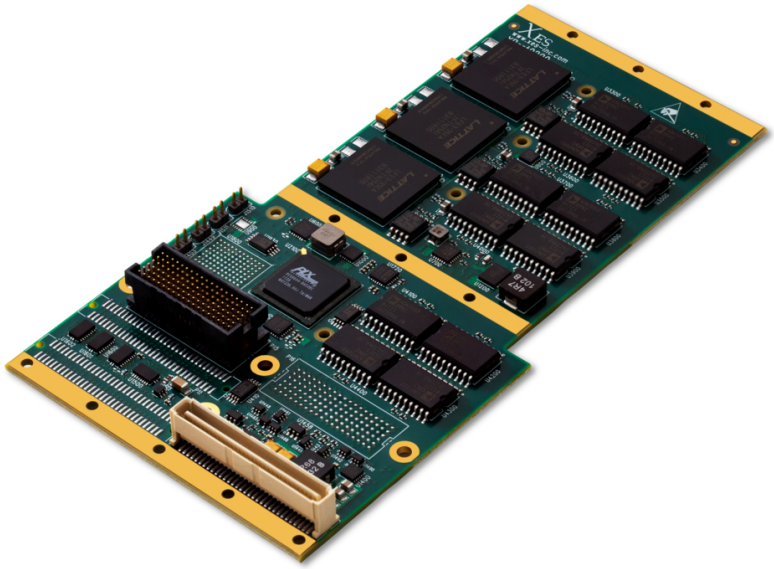
XPort9200

Conduction- or Air-Cooled 12-Channel High-Speed CAN Bus PMC or XMC

- 12 galvanically isolated CAN bus channels
- Compliant with CAN specifications 2.0A (11-Bit-ID) and 2.0B (29-Bit-ID)
- High-speed ISO 11898-2-compliant CAN bus channels
- Up to 1 Mbps per CAN bus channel
- On-card termination (optional)
- Conduction- or air-cooled
- Front panel, PMC P14, or XMC P16 I/O
- XMC PCIe or PMC PCI interface
- Conformal coating available
- NXP SJA1000-compatible CAN Controller (FPGA implementation)
- Linux SocketCAN support
- Wind River VxWorks and Microsoft Windows support



XPort9200

The XPort9200 is a conduction- or air-cooled 12-channel CAN bus XMC or PMC module. Each high-speed CAN bus 2.0 A/B channel is galvanically isolated and supports up to 1 Mbps.

The XPort9200 supports a x1 PCIe XMC or 32-bit PCI PMC interface. All 12 CAN bus channels can be supported through the PMC P14, XMC P16, or front panel connector. Optional on-card termination also is available for each channel.

The XPort9200 utilizes an FPGA implementation of the NXP SJA1000 CAN bus controller and supports Linux SocketCAN. Wind River VxWorks and Microsoft Windows drivers also are available.

X-ES Extreme Engineering Solutions

...Always Fast

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P15 XMC Interface

- VITA 42.3 x1 PCI Express port

P11-P12 PMC Interface

- 32-bit / 66 MHz PCI

Rear I/O PMC/XMC Interface

- 12 CAN bus channels via PMC P14 or XMC P16

Software Support

- Wind River VxWorks BSP
- Linux SocketCAN BSP
- Microsoft Windows drivers

Physical Characteristics

- PMC/XMC conduction- or air-cooled form factor
- Conduction cooling per VITA 20
- Dimensions: 143.75 mm x 74 mm

CAN Bus Interface

- Galvanically isolated
- ISO 11898-2-compliant
- Up to 1 Mbps per channel
- Compliant with CAN specifications 2.0A (11-Bit-ID) and 2.0B (29-Bit-ID)

Configuration Options

- PMC or XMC
- Front panel, P16 or P14 I/O
- Front panel I/O via optional breakout card accessory

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Power will vary based on configuration. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C ambient
Vibration	0.002 g²/Hz, 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing